

Title (en)

METHOD FOR PREVENTING MOLD FORMATION BY USING HYDROPHOBIC MATERIALS, AND MOLD-CONTROLLING AGENT FOR BUILDING PARTS

Title (de)

VERFAHREN ZUR UNTERDRÜCKUNG VON SCHIMMELBILDUNG UNTER VERWENDUNG HYDROPHOBER STOFFE SOWIE EIN SCHIMMELPILZHEMMENDES MITTEL FÜR GEBÄUDETEILE

Title (fr)

PROCEDE PERMETTANT D'EMPECHER LA FORMATION DE MOISSISSURES AU MOYEN DE SUBSTANCES HYDROPHOBES, ET AGENT ANTI-MOISSISSURES POUR PARTIES DE BATIMENT

Publication

**EP 1608224 A1 20051228 (DE)**

Application

**EP 04709246 A 20040209**

Priority

- EP 2004050099 W 20040209
- DE 10315128 A 20030403

Abstract (en)

[origin: WO2004086867A1] The invention relates to a method for preventing mold formation on building parts by using hydrophobic materials. Said method is characterized by the fact that a dispersion of hydrophobic particles having an average diameter of 0.005 to 5 µm is applied in an organic dispersing agent to the surface that is to be protected from mold formation, whereupon the dispersing agent is removed. Also disclosed is a mold growth-inhibiting agent for building parts, which is provided with 0.1 to 10 percent by weight of dispersed hydrophobic particles having an average diameter of 0.005 to 5 µm in an organic dispersing agent.

IPC 1-7

**A01N 59/00**; **A01N 25/34**; **A01N 25/04**; **A01N 25/00**; **B05D 5/08**; **B08B 17/06**; **C09D 7/12**; **C09D 5/00**

IPC 8 full level

**A01N 25/04** (2006.01); **A01N 25/34** (2006.01); **A01N 59/00** (2006.01)

CPC (source: EP US)

**A01N 25/04** (2013.01 - EP US); **A01N 25/34** (2013.01 - EP US); **A01N 59/00** (2013.01 - EP US)

Citation (search report)

See references of WO 2004086867A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT RO SE SI SK TR

DOCDB simple family (publication)

**DE 10315128 A1 20041014**; EP 1608224 A1 20051228; JP 2006522067 A 20060928; JP 4778417 B2 20110921; US 2007184981 A1 20070809; US 8563010 B2 20131022; WO 2004086867 A1 20041014

DOCDB simple family (application)

**DE 10315128 A 20030403**; EP 04709246 A 20040209; EP 2004050099 W 20040209; JP 2006505424 A 20040209; US 55184104 A 20040209